Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.018”**

**.018”**

**Top Material: Al**

 **Backside Material: Au**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref: NJ32**

**APPROVED BY: DK DIE SIZE .018” X .018” DATE: 10/18/21**

**MFG: ALLEGRO / SPRAGUE THICKNESS .006” P/N: 2N3823**

**DG 10.1.2**

#### Rev B, 7/1